

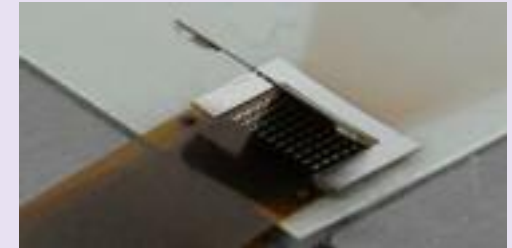
Reference article of new products

**New Arrival !!**

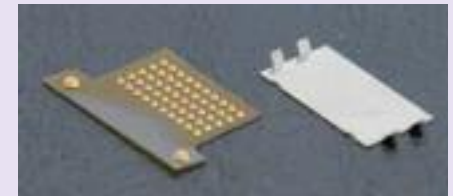
# **UTF Connector** for High Density Flexible Substrate

Patent Pending

UTF connector is ultra thin connector for high density flexible substrate which is new design concept to realize reduction in size and weight of portable electronic device in next generation. Micro bump array formed on the thin substrate realizes high density and connecting high-pin-count within limited space.



- ▶ Mounted height is less than 0.3mm
- ▶ It is possible to connect with more than 60 multi-electrode parts with array connection
- ▶ The flexible substrate pitch is less than 0.3mm
- ▶ The connector is removable
- ▶ Custom designs are available and easily configured
- ▶ The flexible substrate needs no special process



UTF connector will be custom design which follows your request.  
Please visit below websites for more details.

DKN Research ([www.dknresearch.com](http://www.dknresearch.com))  
Hirai Seimitsu Kogyo Corp. ([www.hirai.jp](http://www.hirai.jp))  
NY Industries Ltd. ([www.nyl.co.jp](http://www.nyl.co.jp))

